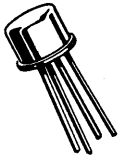


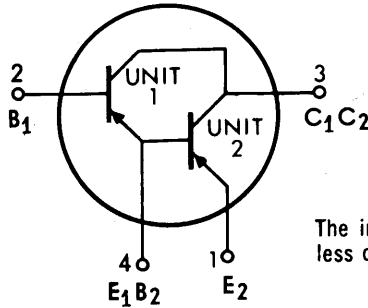
2N4974 (SILICON)

2N4975



PNP silicon annular darlington amplifiers contain two PNP silicon annular transistors connected as a darlington amplifier.

CASE 34A  
(TO-12)



The input unit is identified as Unit 1 regardless of terminal numbering.

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Numerical subscripts refer to unit number

Rating	Symbol	Value	Unit
Collector-Emmitter Voltage (Base 1 and Base 2 open)	V <sub>CE2</sub>	30	Vdc
Collector-Base Voltage	V <sub>CB1</sub>	40	Vdc
Emitter-Base Voltage	V <sub>E2B1</sub>	10	Vdc.
Collector Current – Continuous	I <sub>C</sub>	1.0	Adc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	0.8 4.57	Watt mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	2.5 14.3	Watts mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +200	°C

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Typ	Unit
Thermal Resistance, Junction to Case Output Device Driver Device	θ <sub>JC</sub>	60 85	°C/W
Thermal Resistance, Junction to Junction	θ <sub>JJ</sub>	30	°C/W

# 2N4974, 2N4975 (continued)

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Numerical subscripts refer to unit number, lead 4 open unless otherwise noted.

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector-Emitter Breakdown Voltage * ( $I_C = 10\text{ mAdc}$ , $E_2B_1$ termination open)	$BV_{CE2}^*$	30	40	-	Vdc
Collector-Base Breakdown Voltage ( $I_C = 10\text{ }\mu\text{Adc}$ )	$BV_{CB1O}$	40	50	-	Vdc
Emitter-Base Breakdown Voltage ( $I_{B1} = 10\text{ }\mu\text{Adc}$ )	$BV_{E2B1O}$	10	12.5	-	Vdc
Collector Cutoff Current ( $V_{CB1} = 30\text{ Vdc}$ )	$I_{CB1O}$	-	0.5	10	nAdc
Emitter Cutoff Current ( $V_{E2B1} = 5.0\text{ Vdc}$ )	$I_{E2B1O}$	-	0.15	10	nAdc
<b>ON CHARACTERISTICS</b>					
DC Current Gain ( $I_C = 1.0\text{ }\mu\text{Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )	$h_{FE}$	5,000 1,000	9,000 4,000	- -	-
( $I_C = 1.0\text{ }\mu\text{Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ , $T_A = -55^\circ\text{C}$ )		- -	2,000 1,000	- -	
( $I_C = 10\text{ }\mu\text{Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )		10,000 5,000	15,000 9,000	- -	
( $I_C = 10\text{ }\mu\text{Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ , $T_A = -55^\circ\text{C}$ )		- -	3,500 2,000	- -	
( $I_C = 100\text{ }\mu\text{Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )		20,000 10,000	30,000 20,000	- -	
( $I_C = 1.0\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )		25,000 15,000	50,000 30,000	- -	
( $I_C = 10\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )*		30,000 15,000	60,000 30,000	150,000 75,000	
( $I_C = 10\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ , $T_A = -55^\circ\text{C}$ )*		- -	15,000 10,000	- -	
( $I_C = 100\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )*		25,000 15,000	50,000 30,000	- -	
( $I_C = 500\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )*		15,000 5,000	25,000 10,000	- -	
( $I_C = 1.0\text{ Adc}$ , $V_{CE2} = 5.0\text{ Vdc}$ )*		2,000 1,000	4,000 2,000	- -	
Collector-Emitter Saturation Voltage * ( $I_C = 500\text{ mAdc}$ , $I_{B1} = 1.0\text{ mAdc}$ )	$V_{CE2(sat)}^*$	-	1.4	2.0	Vdc
Base-Emitter Voltage * ( $I_C = 500\text{ mAdc}$ , $I_{B1} = 1.0\text{ mAdc}$ )	$V_{B1E2}^*$	-	2.0	2.7	Vdc
<b>DYNAMIC CHARACTERISTICS</b>					
Current-Gain - Bandwidth Product ( $I_C = 20\text{ mAdc}$ , $V_{CE2} = 5.0\text{ Vdc}$ , $f = 100\text{ MHz}$ )	$f_T$	175	275	-	MHz
Output Capacitance ( $V_{CB1} = 10\text{ Vdc}$ , $I_{E2} = 0$ , $f = 140\text{ kHz}$ )	$C_{ob1}$	-	4.0	8.0	pF
Small-Signal Current Gain ( $I_C = 1.0\text{ mAdc}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{fe}$	25,000 15,000	- -	- -	-
Noise Figure ( $I_C = 1.0\text{ mAdc}$ , $V_{CB1} = 10\text{ Vdc}$ , $R_S = 10\text{ k ohms}$ , $BW = 15.7\text{ kHz}$ )	NF	-	3.0	6.0	dB

\* Pulse Test: Pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$

2N5334 (SILICON)

2N5335

**HIGH-SPEED NPN SILICON POWER TRANSISTORS**

... designed for fast switching and amplifier applications.

- Total Switching Time – 1.15  $\mu$ s Max
- High Current Switching Specified at 1.0 Adc –  
 $t_{on} = 100$  ns Max  
 $t_{off} = 1.05$   $\mu$ s Max
- Collector-Emitter Saturation Voltage –  
 $V_{CE(sat)} = 0.7$  Vdc (Max) @  $I_C = 2.0$  Adc

**MAXIMUM RATINGS**

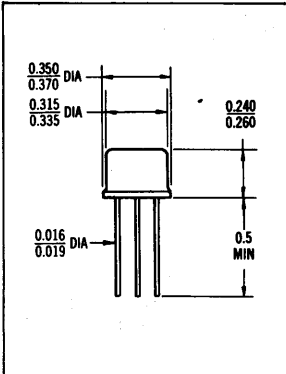
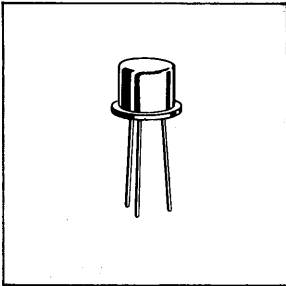
Rating	Symbol	2N5334	2N5335	Unit
Collector-Emitter Voltage	$V_{CEO}$	60	80	Vdc
Collector-Base Voltage	$V_{CB}$	60	80	Vdc
Emitter-Base Voltage	$V_{EB}$	8.0		Vdc
Collector Current - Continuous	$I_C$	3.0		A dc
Base Current - Continuous	$I_B$	0.5		A dc
Total Device Dissipation @ $T_C = 25^\circ$ C Derate above $25^\circ$ C	$P_D$	6.0	34	Watts mW/ $^\circ$ C
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +200		$^\circ$ C

**THERMAL CHARACTERISTICS**

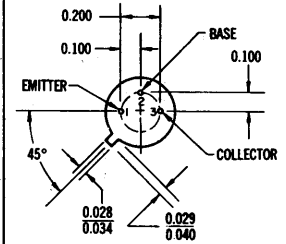
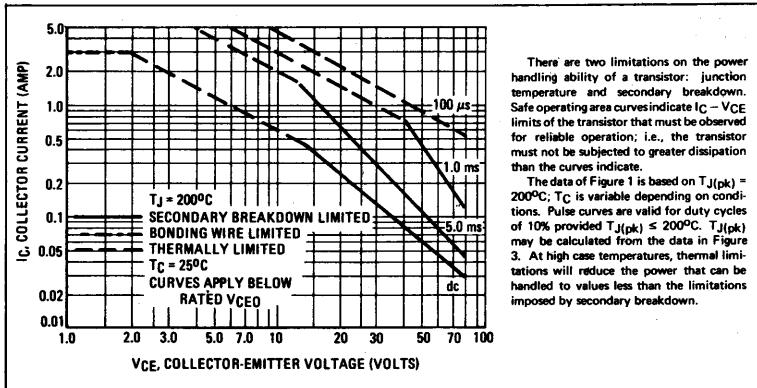
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$\theta_{JC}$	29.1	$^\circ$ C/W

**3 AMPERE  
POWER TRANSISTORS**

**60-80 VOLTS  
6 WATTS**



**FIGURE 1 – ACTIVE-REGION SAFE OPERATING AREA**



**TO-39  
CASE 79**

**ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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**OFF CHARACTERISTICS**

Collector-Emitter Sustaining Voltage* ( $I_C = 50 \text{ mA}$ , $I_B = 0$ )	2N5334 2N5335	$V_{CE(sus)}$ *	60 80	- -	Vdc
Collector Cutoff Current ( $V_{CE} = 60 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ )	2N5334	$I_{CEX}$	-	1.0	$\mu\text{A}$
( $V_{CE} = 80 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ )	2N5335		-	1.0	
( $V_{CE} = 60 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ , $T_C = 150^\circ\text{C}$ )	2N5334		-	500	
( $V_{CE} = 80 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ , $T_C = 150^\circ\text{C}$ )	2N5335		-	500	
Collector Cutoff Current ( $V_{CB} = 60 \text{ Vdc}$ , $I_E = 0$ )	2N5334	$I_{CBO}$	-	5.0	$\mu\text{A}$
( $V_{CB} = 80 \text{ Vdc}$ , $I_E = 0$ )	2N5335		-	5.0	
Emitter Cutoff Current ( $V_{BE} = 8.0 \text{ Vdc}$ , $I_C = 0$ )		$I_{EBO}$	-	100	$\mu\text{A}$

**ON CHARACTERISTICS**

DC Current Gain* ( $I_C = 1.0 \text{ A}$ , $V_{CE} = 2.0 \text{ Vdc}$ ) ( $I_C = 2.0 \text{ A}$ , $V_{CE} = 2.0 \text{ Vdc}$ )	$h_{FE}$ *	30 15	150 -	-
Collector-Emitter Saturation Voltage* ( $I_C = 2.0 \text{ A}$ , $I_B = 0.2 \text{ A}$ )	$V_{CE(sat)}$ *	-	0.7	Vdc
Base-Emitter Saturation Voltage* ( $I_C = 2.0 \text{ A}$ , $I_B = 0.2 \text{ A}$ )	$V_{BE(sat)}$ *	-	1.5	Vdc

**DYNAMIC CHARACTERISTICS**

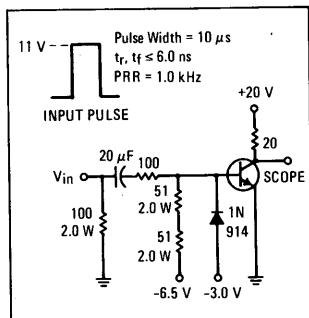
Current-Gain-Bandwidth Product ( $I_C = 0.1 \text{ A}$ , $V_{CE} = 10 \text{ Vdc}$ , $f = 10 \text{ MHz}$ )	$f_T$	60	-	MHz
Output Capacitance ( $V_{CB} = 10 \text{ Vdc}$ , $I_E = 0$ , $f = 100 \text{ kHz}$ )	$C_{ob}$	-	75	pF
Input Capacitance ( $V_{BE} = 2.0 \text{ Vdc}$ , $I_C = 0$ , $f = 100 \text{ kHz}$ )	$C_{ib}$	-	250	pF

**SWITCHING CHARACTERISTICS**

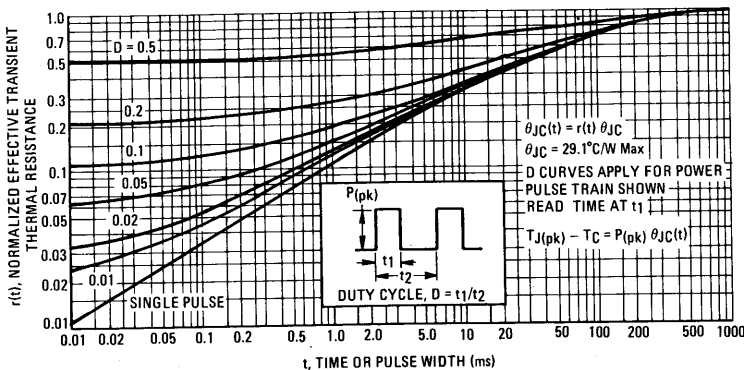
Delay Time	$(V_{CC} = 20 \text{ Vdc}$ , $V_{EB(off)} = 3.7 \text{ Vdc}$ , $I_C = 1.0 \text{ A}$ , $I_{B1} = I_{B2} = 100 \text{ mA}$ ) (See Figure 2)	$t_d$	-	50	ns
Rise Time		$t_r$	-	50	ns
Storage Time		$t_s$	-	950	ns
Fall Time		$t_f$	-	100	ns

\*Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

**FIGURE 2 - SWITCHING TIME CIRCUIT**



**FIGURE 3 - THERMAL RESPONSE**

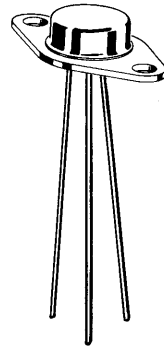


## PNP SILICON ANNULAR EPITAXIAL TRANSISTOR

... designed for high-voltage, high-speed saturated switching at collector currents of 1 Ampere or below. Ideally suited for inverters, deflection circuits and servo amplifiers.

- High Collector-Emitter Sustaining Voltage –  $BV_{CEO(sus)} = 300 \text{ Vdc (Min) @ } I_C = 10 \text{ mAdc}$
- Low Collector-Emitter Saturation Voltage –  $V_{CE(sat)} = 0.3 \text{ Vdc (Typ) @ } I_C = 500 \text{ mAdc}$
- Fast Turn-On Time –  $t_{on} = 60 \text{ ns (Typ) @ } V_{CC} = 100 \text{ Vdc, } I_C = 1.0 \text{ Adc}$
- Fast Turn-Off Time –  $t_{off} = 280 \text{ ns (Typ) @ } V_{CC} = 100 \text{ Vdc, } I_C = 1.0 \text{ Adc}$

## PNP SILICON SWITCHING TRANSISTOR



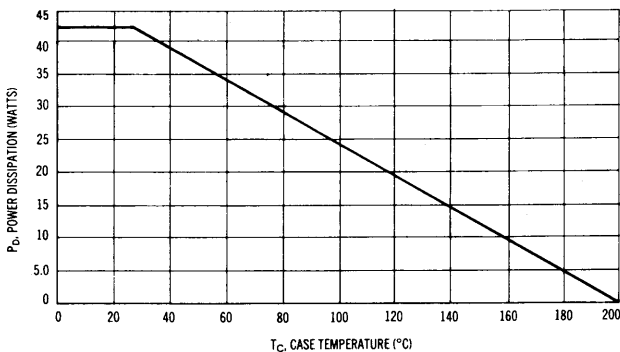
### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	300	Vdc
Collector-Base Voltage	$V_{CB}$	300	Vdc
Emitter-Base Voltage	$V_{EB}$	5.0	Vdc
Collector Current - Continuous	$I_C$	3.0	Adc
Base Current - Continuous	$I_B$	1.0	Adc
Total Device Dissipation @ $T_C = 75^\circ\text{C}$ Derate above $75^\circ\text{C}$	$P_D$	30 240	Watts mW/°C
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +200	°C

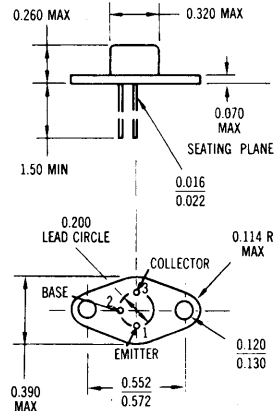
### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$\theta_{JC}$	4.16	°C/W

FIGURE 1 – POWER-TEMPERATURE DERATING CURVE



Safe Area Curves Are Indicated By Figure 5. All Limits Are Applicable And Must Be Observed.



Collector Connected to Case  
Case 39  
TO-37

ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Collector-Emitter Sustaining Voltage ( $I_C = 10 \text{ mA}$ , $I_B = 0$ )	$V_{CE(sus)}$	300	-	Vdc
Collector-Base Breakdown Voltage ( $I_C = 100 \mu\text{A}$ , $I_E = 0$ )	$V_{CBO}$	300	-	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 100 \mu\text{A}$ , $I_C = 0$ )	$V_{EBO}$	5.0	-	Vdc
Collector Cutoff Current ( $V_{CE} = 200 \text{ Vdc}$ , $V_{BE(off)} = 0.5 \text{ Vdc}$ , $T_A = 100^\circ\text{C}$ ) ( $V_{CE} = 300 \text{ Vdc}$ , $V_{BE(off)} = 0.5 \text{ Vdc}$ )	$I_{CEX}$	-	100	$\mu\text{A}$
Emitter Cutoff Current ( $V_{BE} = 3.0 \text{ Vdc}$ , $I_C = 0$ ) ( $V_{BE} = 5.0 \text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	-	100	nA
		-	100	$\mu\text{A}$

ON CHARACTERISTICS

DC Current Gain ( $I_C = 500 \mu\text{A}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 10 \text{ mA}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 100 \text{ mA}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 100 \text{ mA}$ , $V_{CE} = 1.0 \text{ Vdc}$ , $T_A = -55^\circ\text{C}$ ) ( $I_C = 500 \text{ mA}$ , $V_{CE} = 5.0 \text{ Vdc}$ ) ( $I_C = 1.0 \text{ A}$ , $V_{CE} = 5.0 \text{ Vdc}$ )	$h_{FE}$	45 50 40 20 25 10	- - - - 100 -	- - - - - -
Collector-Emitter Saturation Voltage ( $I_C = 100 \text{ mA}$ , $I_B = 10 \text{ mA}$ ) ( $I_C = 500 \text{ mA}$ , $I_B = 50 \text{ mA}$ ) ( $I_C = 1.0 \text{ A}$ , $I_B = 100 \text{ mA}$ )	$V_{CE(sat)}$	- - -	0.3 1.0 3.0	Vdc
Base-Emitter Saturation Voltage ( $I_C = 100 \text{ mA}$ , $I_B = 10 \text{ mA}$ ) ( $I_C = 500 \text{ mA}$ , $I_B = 50 \text{ mA}$ ) ( $I_C = 1.0 \text{ A}$ , $I_B = 100 \text{ mA}$ )	$V_{BE(sat)}$	- - -	1.0 1.3 1.5	Vdc

DYNAMIC CHARACTERISTICS

Current-Gain-Bandwidth Product ( $I_C = 70 \text{ mA}$ , $V_{CE} = 20 \text{ Vdc}$ , $f = 20 \text{ MHz}$ )	$f_T$	50	-	MHz
Output Capacitance ( $V_{CB} = 20 \text{ Vdc}$ , $I_E = 0$ , $f = 100 \text{ kHz}$ )	$C_{ob}$	-	60	pF
Input Capacitance ( $V_{BE} = 2.0 \text{ Vdc}$ , $I_C = 0$ , $f = 100 \text{ kHz}$ )	$C_{ib}$	-	600	pF

SWITCHING CHARACTERISTICS

Delay Time	( $V_{CC} = 100 \text{ Vdc}$ , $I_C = 500 \text{ mA}$ , $I_B = 50 \text{ mA}$ ) (See Figure 2)	$t_d$	-	50	ns
Rise Time		$t_r$	-	100	ns
Storage Time	( $V_{CC} = 100 \text{ Vdc}$ , $I_C = 500 \text{ mA}$ , $I_{B1} = I_{B2} = 50 \text{ mA}$ ) (See Figure 2)	$t_s$	-	600	ns
Fall Time		$t_f$	-	100	ns

FIGURE 2 - SWITCHING TIME TEST CIRCUIT

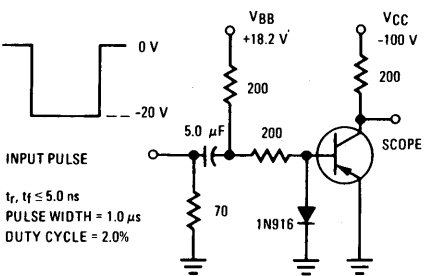


FIGURE 3 - TURN-ON TIME

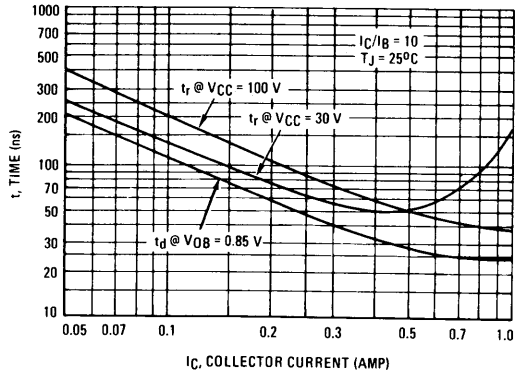


FIGURE 4 – THERMAL RESPONSE

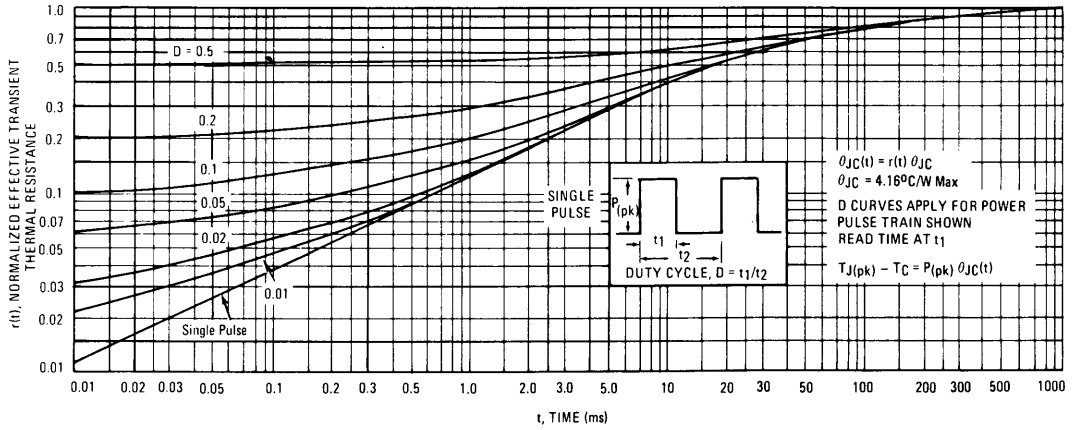
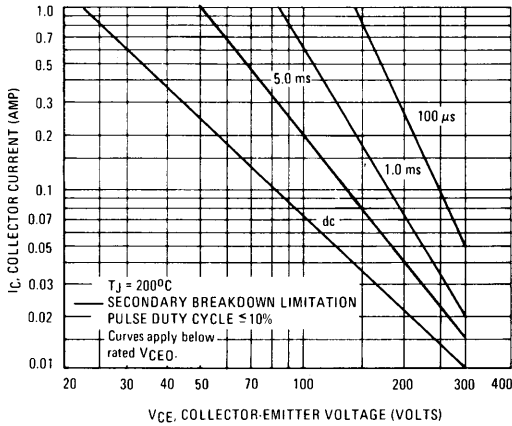


FIGURE 5 – ACTIVE-REGION SAFE OPERATING AREA



There are two limitations on the power handling ability of a transistor: junction temperature and secondary breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_{J(pk)} = 200^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Pulse curves are valid for duty cycles of 10% provided  $T_{J(pk)} \leq 200^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by secondary breakdown.

FIGURE 6 – TURN-OFF TIME

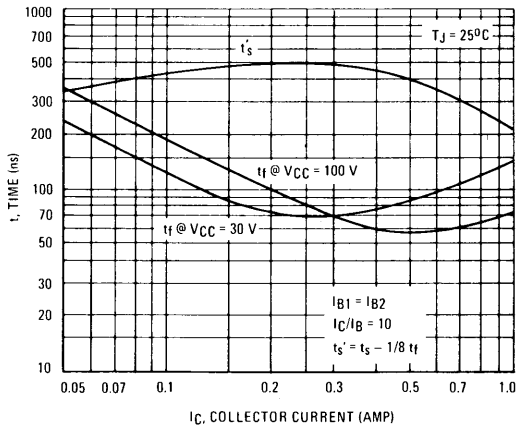
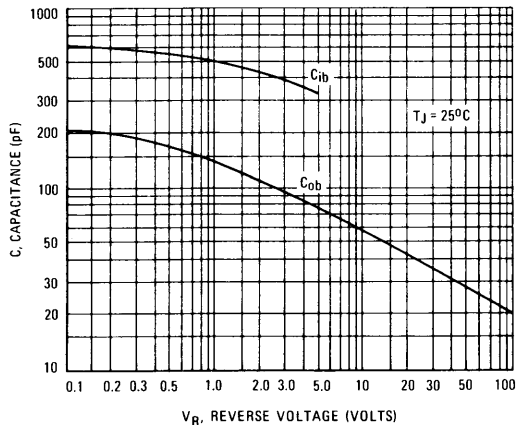


FIGURE 7 – CAPACITANCES



TYPICAL DC CHARACTERISTICS

FIGURE 8 - DC CURRENT GAIN

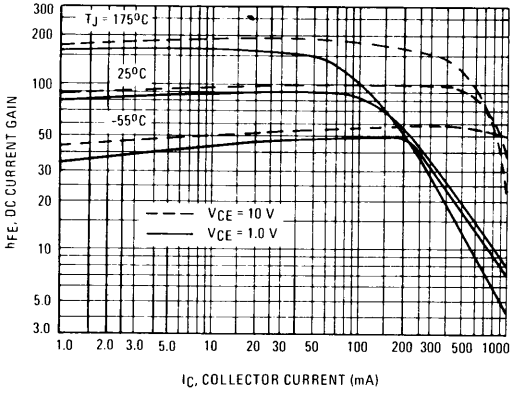


FIGURE 9 - COLLECTOR SATURATION REGION

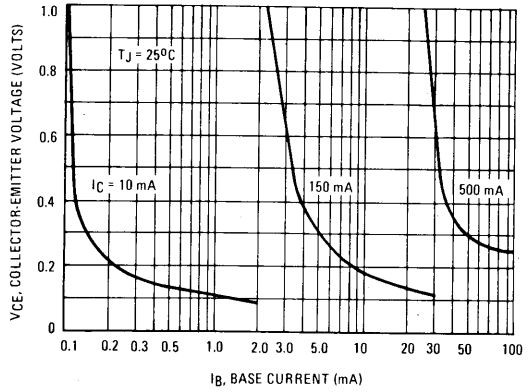


FIGURE 10 - EFFECTS OF BASE-EMITTER RESISTANCE

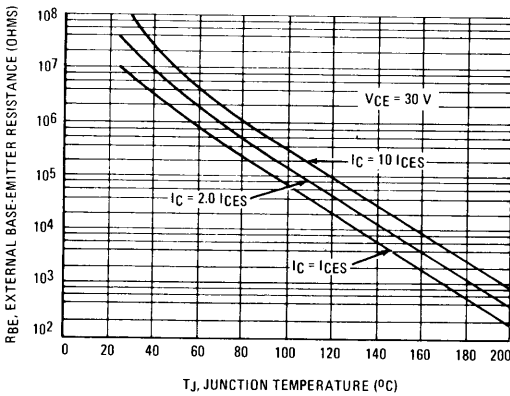


FIGURE 11 - "ON" VOLTAGES

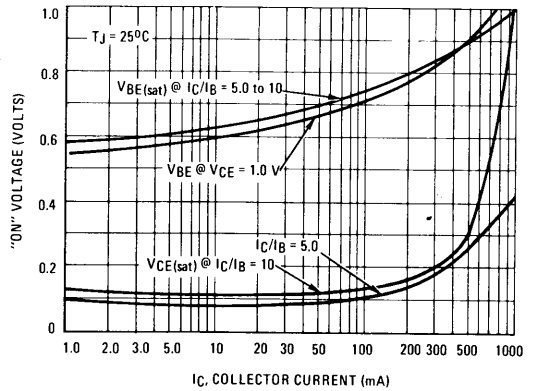


FIGURE 12 - COLLECTOR CUT-OFF REGION

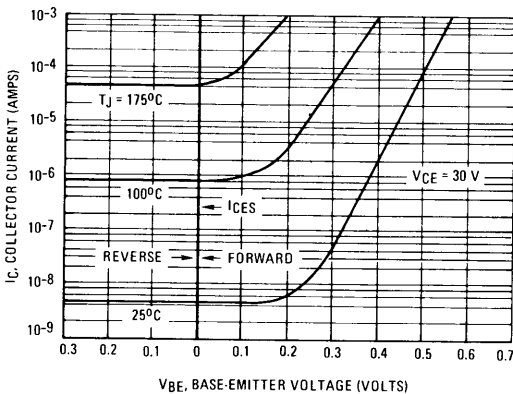
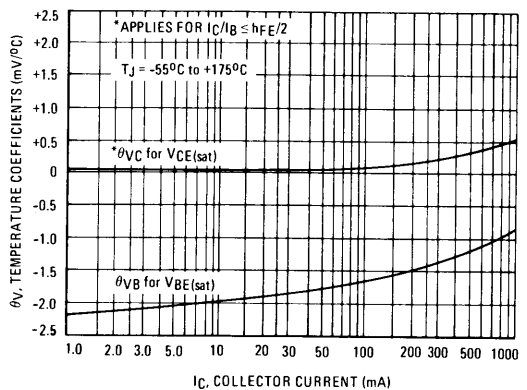


FIGURE 13 - TEMPERATURE COEFFICIENTS





2N5477 (SILICON)

thru

2N5480

**MEDIUM-POWER NPN SILICON TRANSISTORS**

... designed for switching and wide-band amplifier applications.

- Low Collector Emitter Saturation Voltage –  $V_{CE(sat)} = 1.2 \text{ Vdc (Max) @ } I_C = 7.0 \text{ Adc}$
- DC Current Gain Specified to 5 Amperes
- Excellent Safe Operating Area
- Packaged in the Compact, High Dissipation TO-59 Case
- Collector Common to Case

**7 AMPERE  
POWER TRANSISTORS**

**NPN SILICON**

**80-100 VOLTS  
60 WATTS**

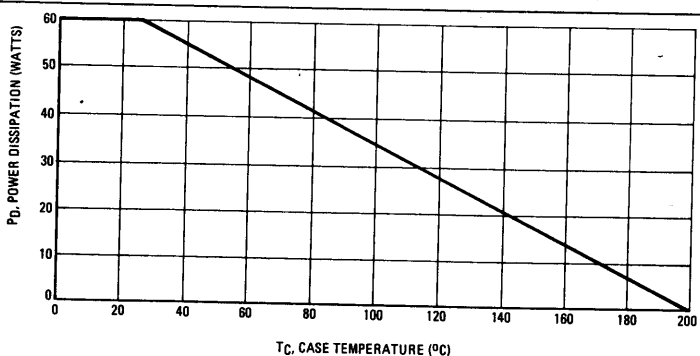
**MAXIMUM RATINGS**

Rating	Symbol	2N5477 2N5478	2N5479 2N5480	Unit
Collector-Emitter Voltage	$V_{CEO}$	80	100	Vdc
Collector-Base Voltage	$V_{CB}$	80	100	Vdc
Emitter-Base Voltage	$V_{EB}$	6.0		Vdc
Collector Current – Continuous	$I_C$	7.0		A dc
Base Current - Continuous	$I_B$	1.0		A dc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	60		Watts
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +200		$^\circ\text{C}$

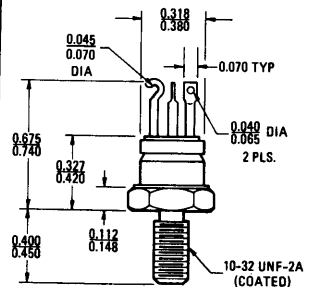
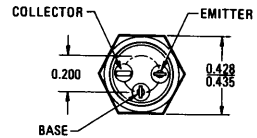
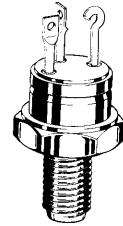
**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$\theta_{JC}$	2.91	$^\circ\text{C/W}$

**FIGURE 1 – POWER-TEMPERATURE DERATING CURVE**



Safe Area Curves are indicated by Figure 5. All limits are applicable and must be observed.



CASE 160 A  
(TO-59)

Collector Common  
To Case

**ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Fig. No.	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector-Emitter Sustaining Voltage* ( $I_C = 50\text{ mAdc}$ , $I_B = 0$ )	2N5477, 2N5478 2N5479, 2N5480	$V_{CE(sus)}$ *	80 100	- -	Vdc
Collector Cutoff Current ( $V_{CE} = 75\text{ Vdc}$ , $I_B = 0$ ) ( $V_{CE} = 90\text{ Vdc}$ , $I_B = 0$ )	2N5477, 2N5478 2N5479, 2N5480	$I_{CEO}$	- -	100 100	$\mu\text{Adc}$
Collector Cutoff Current ( $V_{CE} = 75\text{ Vdc}$ , $V_{EB(off)} = 1.5\text{ Vdc}$ ) ( $V_{CE} = 90\text{ Vdc}$ , $V_{EB(off)} = 1.5\text{ Vdc}$ ) ( $V_{CE} = 75\text{ Vdc}$ , $V_{EB(off)} = 1.5\text{ Vdc}$ , $T_C = 150^\circ\text{C}$ ) ( $V_{CE} = 90\text{ Vdc}$ , $V_{EB(off)} = 1.5\text{ Vdc}$ , $T_C = 150^\circ\text{C}$ )	2N5477, 2N5478 2N5479, 2N5480 2N5477, 2N5478 2N5479, 2N5480	$I_{CEX}$	- - - -	10 10 1.0 1.0	$\mu\text{Adc}$  mAdc
Collector Cutoff Current ( $V_{CB} = \text{Rated } V_{CB}$ , $I_E = 0$ )	-	$I_{CBO}$	-	10	$\mu\text{Adc}$
Emitter Cutoff Current ( $V_{BE} = 6.0\text{ Vdc}$ , $I_C = 0$ )	-	$I_{EBO}$	-	100	$\mu\text{Adc}$

**ON CHARACTERISTICS**

DC Current Gain* ( $I_C = 500\text{ mAdc}$ , $V_{CE} = 2.0\text{ Vdc}$ )  ( $I_C = 2.0\text{ Adc}$ , $V_{CE} = 2.0\text{ Vdc}$ )  ( $I_C = 5.0\text{ Adc}$ , $V_{CE} = 2.0\text{ Vdc}$ )	2N5477, 2N5479 2N5478, 2N5480 2N5477, 2N5479 2N5478, 2N5480 2N5477, 2N5479 2N5478, 2N5480	8	$h_{FE}$ *	30 60 30 60 20 40	- - 120 240 - -	-
Collector-Emitter Saturation Voltage* ( $I_C = 2.0\text{ Adc}$ , $I_B = 0.2\text{ Adc}$ ) ( $I_C = 7.0\text{ Adc}$ , $I_B = 0.7\text{ Adc}$ )		9, 11, 13	$V_{CE(sat)}$ *	- -	0.7 1.2	Vdc
Base-Emitter Saturation Voltage* ( $I_C = 2.0\text{ Adc}$ , $I_B = 0.2\text{ Adc}$ ) ( $I_C = 7.0\text{ Adc}$ , $I_B = 0.7\text{ Adc}$ )		11, 13	$V_{BE(sat)}$ *	- -	1.2 2.0	Vdc

**DYNAMIC CHARACTERISTICS**

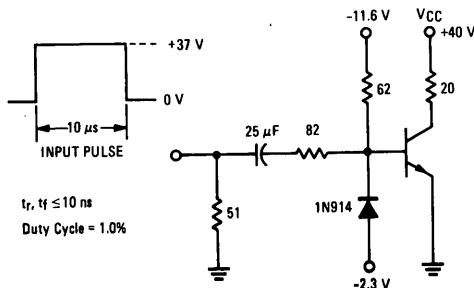
Current-Gain-Bandwidth Product ( $I_C = 500\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 10\text{ MHz}$ )	-	$f_T$	30	-	MHz
Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f = 100\text{ kHz}$ )	7	$C_{ob}$	-	250	pF
Input Capacitance ( $V_{BE} = 2.0\text{ Vdc}$ , $I_C = 0$ , $f = 100\text{ kHz}$ )	7	$C_{ib}$	-	1,000	pF

**SWITCHING CHARACTERISTICS**

Delay Time	( $V_{CC} = 40\text{ Vdc}$ , $V_{EB(off)} = 3.0\text{ Vdc}$ , $I_C = 2.0\text{ Adc}$ , $I_{B1} = 200\text{ mAdc}$ )	2,3	$t_d$	-	100	ns
Rise Time			$t_r$	-	100	ns
Storage Time	( $V_{CC} = 40\text{ Vdc}$ , $I_C = 2.0\text{ Adc}$ , $I_{B1} = I_{B2} = 200\text{ mAdc}$ )	2,6	$t_s$	-	2.0	$\mu\text{s}$
Fall Time			$t_f$	-	200	ns

\* Pulse Test: Pulse Width  $\approx 300\ \mu\text{s}$ , Duty Cycle  $\approx 2.0\%$ .

**FIGURE 2 - SWITCHING TIME TEST CIRCUIT**



**FIGURE 3 - TURN-ON TIME**

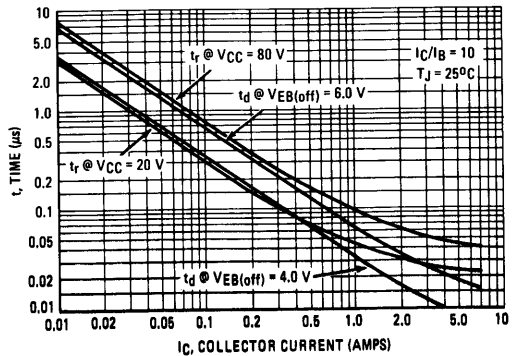


FIGURE 4 – THERMAL RESPONSE

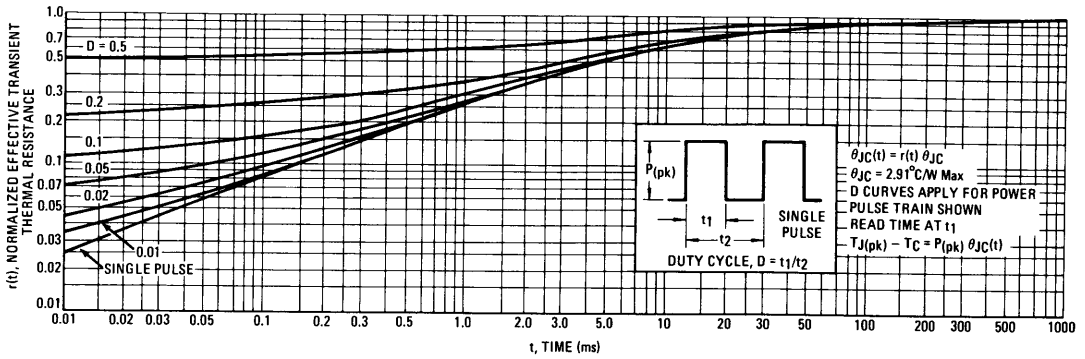
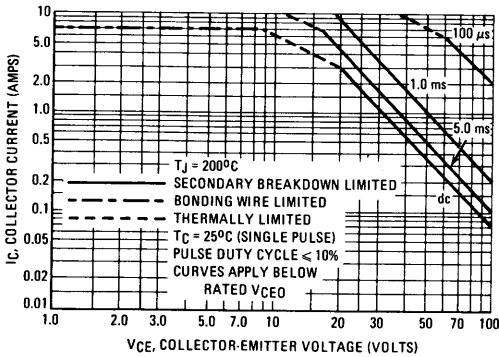


FIGURE 5 – ACTIVE-REGION SAFE OPERATING AREA



There are two limitations on the power handling ability of a transistor: junction temperature and secondary breakdown. Safe operating area curves indicate  $I_C$ - $V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_J(pk) = 200^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Pulse curves are valid for duty cycles of 10% provided  $T_J(pk) \leq 200^\circ\text{C}$ .  $T_J(pk)$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by secondary breakdown.

FIGURE 6 – TURN-OFF TIME

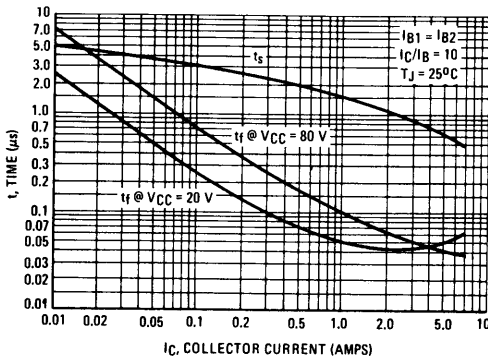


FIGURE 7 – CAPACITANCE versus VOLTAGE

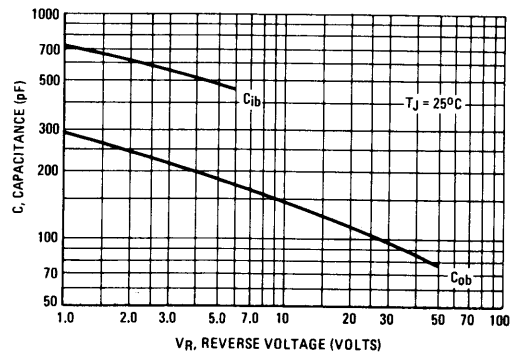


FIGURE 8 — DC CURRENT GAIN

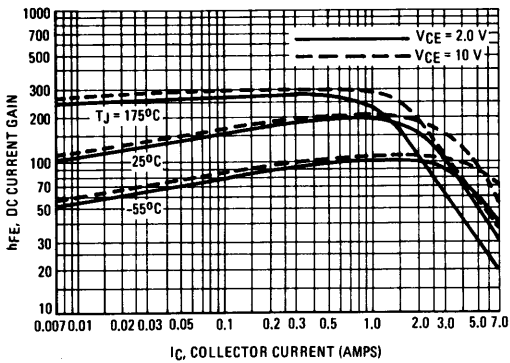


FIGURE 9 — COLLECTOR SATURATION REGION

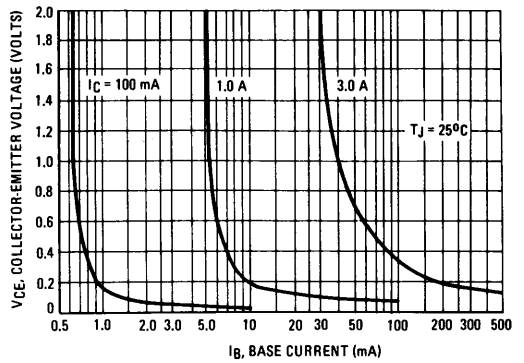


FIGURE 10 — EFFECTS OF BASE-EMITTER RESISTANCE

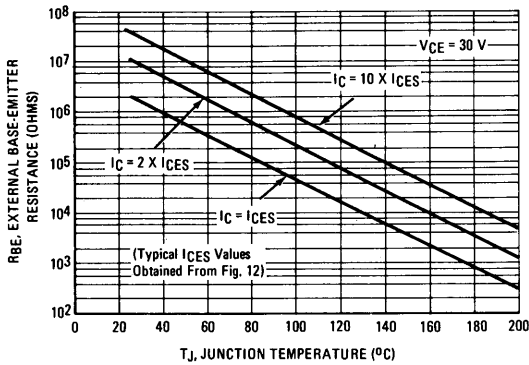


FIGURE 11 — "ON" VOLTAGES

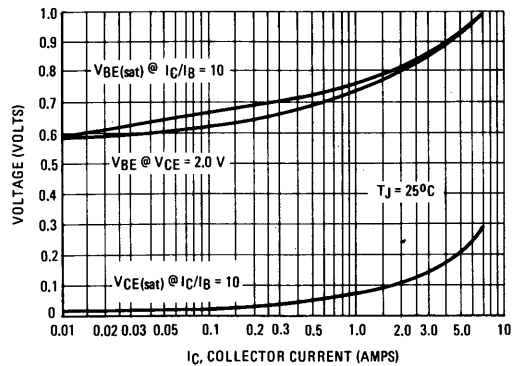


FIGURE 12 — COLLECTOR CUT-OFF REGION

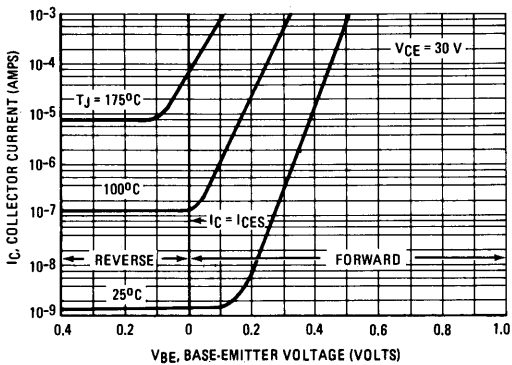
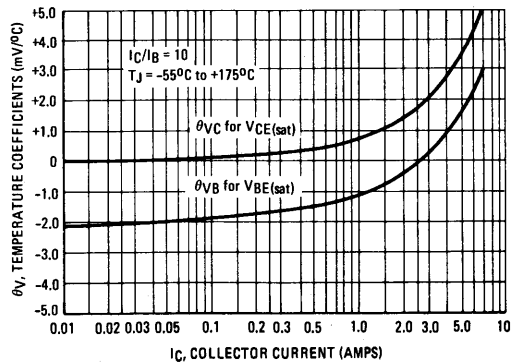
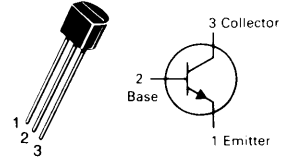


FIGURE 13 — TEMPERATURE COEFFICIENTS



# 2N6428,A

CASE 29-04, STYLE 1  
TO-92 (TO-226AA)



AMPLIFIER TRANSISTOR

NPN SILICON

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CE0}$	50	Vdc
Collector-Base Voltage	$V_{CBO}$	60	Vdc
Emitter-Base Voltage	$V_{EBO}$	6.0	Vdc
Collector Current — Continuous	$I_C$	200	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	625 5.0	mW mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.5 12	Watts mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector-Emitter Breakdown Voltage ( $I_C = 1.0$ mAdc, $I_B = 0$ )	$V_{(BR)CEO}$	50	—	Vdc
Collector-Base Breakdown Voltage ( $I_C = 0.1$ mAdc, $I_E = 0$ )	$V_{(BR)CBO}$	60	—	Vdc
Collector Cutoff Current ( $V_{CE} = 30$ Vdc)	$I_{CEO}$	—	0.025	$\mu\text{A}$
Collector Cutoff Current ( $V_{CB} = 30$ Vdc, $I_E = 0$ )	$I_{CBO}$	—	0.01	$\mu\text{A}$
Emitter Cutoff Current ( $V_{EB} = 5.0$ Vdc, $I_C = 0$ )	$I_{EBO}$	—	0.01	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $V_{CE} = 5.0$ Vdc, $I_C = 0.01$ mAdc) ( $V_{CE} = 5.0$ Vdc, $I_C = 0.1$ mAdc) ( $V_{CE} = 5.0$ Vdc, $I_C = 1.0$ mAdc) ( $V_{CE} = 5.0$ Vdc, $I_C = 10$ mAdc)	$h_{FE}$	250 250 250 250	— 650 — —	—
Collector-Emitter Saturation Voltage ( $I_C = 10$ mAdc, $I_B = 0.5$ mAdc) ( $I_C = 100$ mAdc, $I_B = 5.0$ mAdc)	$V_{CE(sat)}$	— —	0.2 0.6	Vdc
Base-Emitter On Voltage ( $I_C = 1.0$ mAdc, $V_{CE} = 5.0$ Vdc)	$V_{BE(on)}$	0.56	0.66	Vdc
<b>SMALL-SIGNAL CHARACTERISTICS</b>				
Current-Gain — Bandwidth Product ( $I_C = 1.0$ mAdc, $V_{CE} = 5.0$ V, $f = 100$ MHz)	$f_T$	100	700	MHz
Output Capacitance ( $V_{CB} = 10$ Vdc, $I_E = 0$ , $f = 1.0$ MHz)	$C_{obo}$	—	3.0	pF
Input Capacitance ( $V_{EB} = 0.5$ Vdc, $I_C = 0$ , $f = 1.0$ MHz)	$C_{ibo}$	—	8.0	pF

**2N6428,A**

**ELECTRICAL CHARACTERISTICS** (continued) ( $T_A = 25^\circ\text{C}$  unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
Input Impedance ( $I_C = 1.0\text{ mA}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{ie}$	3.0	30	$k\Omega$
Voltage Feedback Ratio ( $I_C = 1.0\text{ mA}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{re}$	2.0	20	$\times 10^{-4}$
Small-Signal Current Gain ( $I_C = 1.0\text{ mA}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{fe}$	200	800	—
Output Admittance ( $I_C = 1.0\text{ mA}$ , $V_{CE} = 5.0\text{ Vdc}$ , $f = 1.0\text{ kHz}$ )	$h_{oe}$	5.0	50	$\mu\text{mhos}$

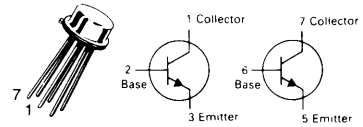
**NOISE FIGURE/TOTAL NOISE VOLTAGE CHARACTERISTICS**

		NF $V_T$		NF $V_T$		NF $V_T$		Unit	
		Max (1)		Max (2)		Max (3)			
Noise Figure/Voltage ( $V_{CE} = 5.0\text{ V}$ , $I_C = 0.1\text{ mA}$ , $T_A = 25^\circ\text{C}$ )	2N6428	3.0	18.1	6.0	5700	3.5	4.3	dB	nV
	2N6428A	2.0	16.2	4.0	4600	3.0	4.1	dB	nV

- (1)  $R_S = 10\text{ k}\Omega$ , BW = 1.0 Hz,  $f = 100\text{ Hz}$
- (2)  $R_S = 50\text{ k}\Omega$ , BW = 15.7 kHz,  $f = 10\text{ Hz}-10\text{ kHz}$
- (3)  $R_S = 500\ \Omega$ , BW = 1.0 Hz,  $f = 10\text{ Hz}$

# 2N6502

CASE 654-07, STYLE 1



**DUAL  
SWITCHING TRANSISTOR**

**NPN SILICON**

## MAXIMUM RATINGS

Rating	Symbol	Value		Unit
Collector-Emitter Voltage	$V_{CEO}$	40		Vdc
Collector-Base Voltage	$V_{CES}$	80		Vdc
Collector-Base Voltage	$V_{CBO}$	80		Vdc
Emitter-Base Voltage	$V_{EBO}$	6.0		Vdc
Collector Current — Continuous	$I_C$	1.0		Adc
		<b>One Die</b>	<b>All Die Equal Power</b>	
Total Device Dissipation ( $\alpha T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$ )	$P_D$	600 3.42	650 3.7	mW mW/ $^\circ\text{C}$
Total Device Dissipation ( $\alpha T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$ )	$P_D$	2.1 12	3.0 17.2	Watts mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	- 65 to + 200		$^\circ\text{C}$

## THERMAL CHARACTERISTICS

Characteristic	Symbol	One Die	All Die Equal Power	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	58.3	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient(1)	$R_{\theta JA}$	292	270	$^\circ\text{C}/\text{W}$
		<b>Junction to Ambient</b>	<b>Junction to Case</b>	
Coupling Factor		85	40	

(1)  $R_{\theta JA}$  is measured with the device soldered into a typical printed circuit board.

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector-Emitter Breakdown Voltage(2) ( $I_C = 10 \text{ mAdc}, I_B = 0$ )	$V_{(BR)CEO}$	40	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 100 \mu\text{Adc}, V_{BE} = 0$ )	$V_{(BR)CES}$	80	—	Vdc
Collector-Base Breakdown Voltage ( $I_C = 100 \mu\text{Adc}, I_E = 0$ )	$V_{(BR)CBO}$	80	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 10 \mu\text{Adc}, I_C = 0$ )	$V_{(BR)EBO}$	6.0	—	Vdc
Collector Cutoff Current ( $V_{CB} = 40 \text{ Vdc}, I_E = 0$ )	$I_{CBO}$	—	1.7	$\mu\text{Adc}$

**ELECTRICAL CHARACTERISTICS** (continued) ( $T_A = 25^\circ\text{C}$  unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
Emitter Cutoff Current ( $V_{BE} = 4.0\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	—	1.0	$\mu\text{Adc}$
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $I_C = 100\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ ) ( $I_C = 500\text{ mAdc}$ , $V_{CE} = 2.0\text{ Vdc}$ ) ( $I_C = 500\text{ mAdc}$ , $V_{CE} = 1.0\text{ Vdc}$ )	$h_{FE}$	50 30 10	150 — —	—
Collector-Emitter Saturation Voltage ( $I_C = 100\text{ mAdc}$ , $I_B = 10\text{ mAdc}$ ) ( $I_C = 500\text{ mAdc}$ , $I_B = 50\text{ mAdc}$ )	$V_{CE(sat)}$	— —	0.3 0.5	Vdc
Base-Emitter Saturation Voltage ( $I_C = 500\text{ mAdc}$ , $I_B = 50\text{ mAdc}$ )	$V_{BE(sat)}$	0.8	1.2	Vdc
<b>SMALL-SIGNAL CHARACTERISTICS</b>				
Current-Gain — Bandwidth Product ( $I_C = 50\text{ mAdc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 100\text{ MHz}$ )	$f_T$	250	—	MHz
Collector-Base Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f = 100\text{ kHz}$ )	$C_{cb}$	—	10	pF
Emitter-Base Capacitance ( $V_{BE} = 0.5\text{ Vdc}$ , $I_C = 0$ , $f = 100\text{ kHz}$ )	$C_{eb}$	—	65	pF
<b>SWITCHING CHARACTERISTICS</b>				
Turn-On Time ( $V_{CC} = 30\text{ Vdc}$ , $V_{BE} = 3.8\text{ Vdc}$ , $I_C = 500\text{ mAdc}$ , $I_{B1} = 50\text{ mAdc}$ )	$t_{on}$	—	35	ns
Turn-Off Time ( $V_{CC} = 30\text{ Vdc}$ , $I_C = 500\text{ mAdc}$ , $I_{B1} = I_{B2} = 50\text{ mAdc}$ )	$t_{off}$	—	60	ns

(2) Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

**TYPICAL DC CHARACTERISTICS**

FIGURE 1 — DC CURRENT GAIN

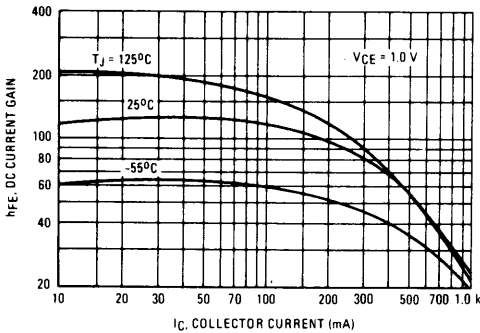


FIGURE 2 — "ON" VOLTAGES

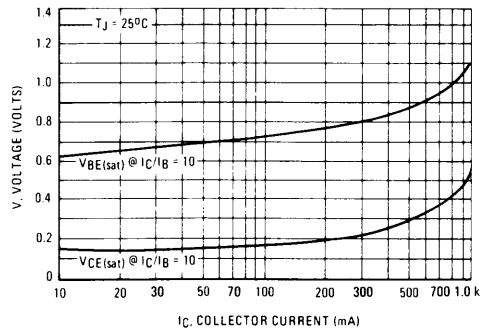




FIGURE 3 – COLLECTOR SATURATION REGION

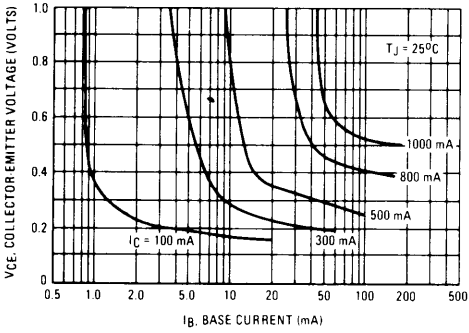
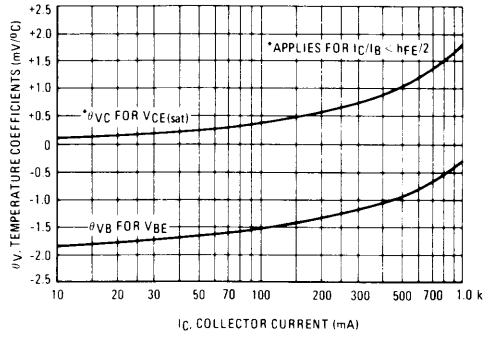


FIGURE 4 – TEMPERATURE COEFFICIENTS



TYPICAL DYNAMIC CHARACTERISTICS

FIGURE 5 – CURRENT-GAIN – BANDWIDTH PRODUCT

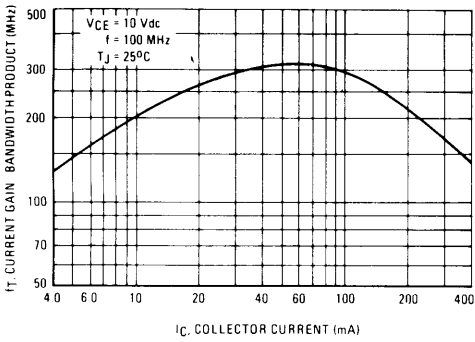


FIGURE 6 – CAPACITANCE

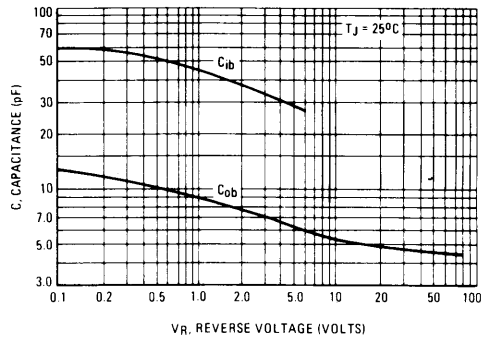


FIGURE 7 – TURN-ON TIME

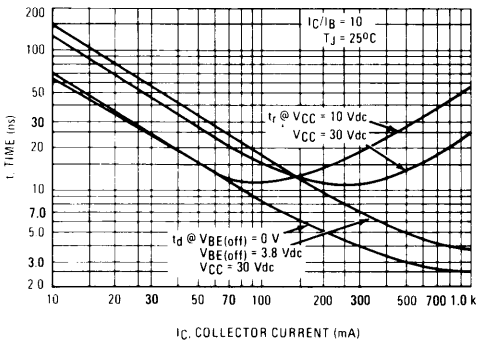


FIGURE 8 – TURN-OFF TIME

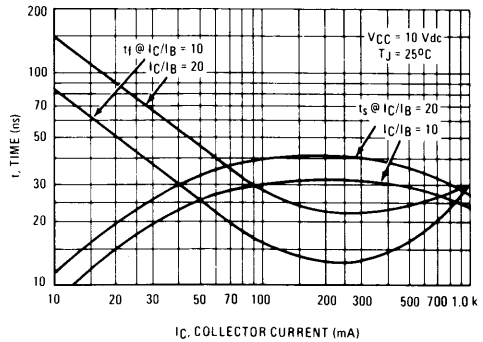


FIGURE 9 – SWITCHING TIME TEST CIRCUIT

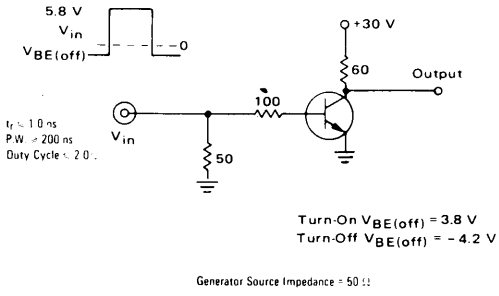
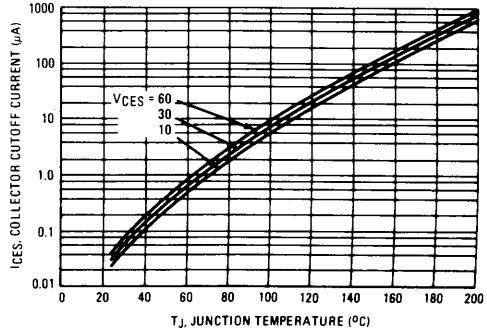


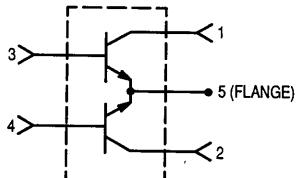
FIGURE 10 – COLLECTOR CUTOFF CURRENT



The RF Line  
**NPN Silicon Push-Pull**  
**RF Power Transistor**

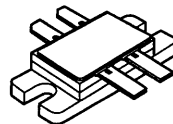
... designed primarily for wideband large-signal output and driver amplifier stages in the 30 to 400 MHz frequency range.

- Specified 28 Volt, 400 MHz Characteristics —  
 Output Power = 125 W  
 Typical Gain = 10 dB (Class C), 11 dB (Class AB)  
 Efficiency = 55% (Typ)
- Hermetic Package to Meet Stringent Environmental Requirements
- Built-In Input Impedance Matching Networks for Broadband Operation
- Push-Pull Configuration Reduces Even Numbered Harmonics
- Gold Metallization System for High Reliability
- 100% Tested for Load Mismatch



**2N6985**

**125 W, 30 to 400 MHz**  
**CONTROLLED "Q"**  
**BROADBAND PUSH-PULL**  
**RF POWER TRANSISTOR**  
**NPN SILICON**



**CASE 382, STYLE 1**

The 2N6985 is two transistors in a single package with separate base and collector leads and emitters common. This arrangement provides the designer with a space saving device capable of operation in a push-pull configuration.

**MAXIMUM RATINGS\***

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	30	Vdc
Collector-Base Voltage	$V_{CBO}$	60	Vdc
Emitter-Base Voltage	$V_{EBO}$	4.0	Vdc
Collector Current — Continuous	$I_C$	16	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ (1) Derate above $25^\circ\text{C}$	$P_D$	270 1.54	Watts W/ $^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-65 to +150	$^\circ\text{C}$
Junction Temperature	$T_J$	200	$^\circ\text{C}$

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.65	$^\circ\text{C}/\text{W}$

**NOTE:**

1. These devices are designed for RF operation. The total device dissipation rating applies only when the devices are operated as RF push-pull amplifiers.

\* Indicates JEDEC Registered Data.

**ELECTRICAL CHARACTERISTICS\*** ( $T_C = 25^\circ\text{C}$  unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS (1)</b>					
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $I_B = 0$ )	$V_{(BR)CEO}$	30	—	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $V_{BE} = 0$ )	$V_{(BR)CES}$	60	—	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 5.0 \text{ mAdc}$ , $I_C = 0$ )	$V_{(BR)EBO}$	4.0	—	—	Vdc
Collector Cutoff Current ( $V_{CB} = 30 \text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	—	—	5.0	mAdc

**ON CHARACTERISTICS (1)**

DC Current Gain ( $I_C = 1.0 \text{ Adc}$ , $V_{CE} = 5.0 \text{ Vdc}$ )	$h_{FE}$	20	—	100	—
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**DYNAMIC CHARACTERISTICS (1)**

Output Capacitance ( $V_{CB} = 28 \text{ Vdc}$ , $I_E = 0$ , $f = 1.0 \text{ MHz}$ )	$C_{ob}$	—	75	115	pF
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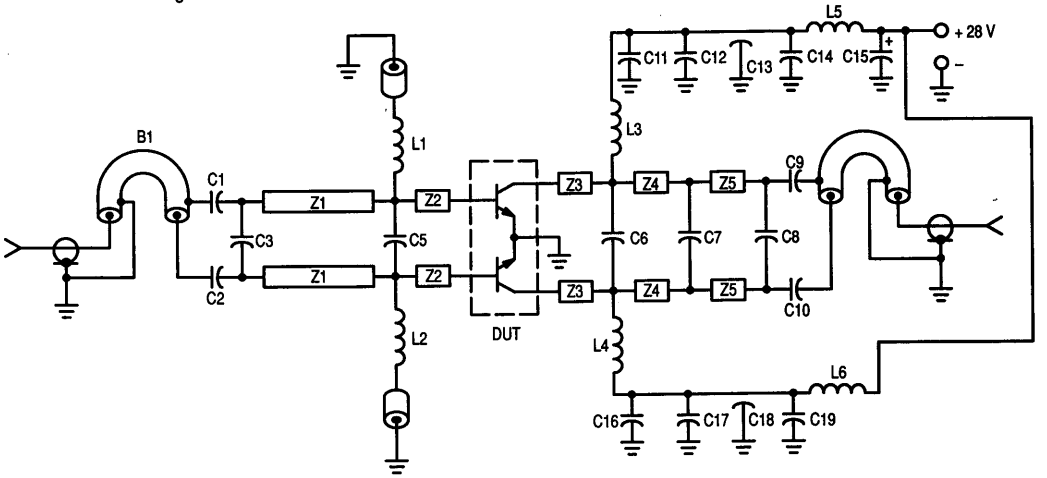
**FUNCTIONAL TESTS (2) — See Figure 1**

Common-Emitter Amplifier Power Gain ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 125 \text{ W}$ , $f = 400 \text{ MHz}$ )	$G_{pe}$	8.0	10	—	dB
Collector Efficiency ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 125 \text{ W}$ , $f = 400 \text{ MHz}$ )	$\eta$	50	55	—	%
Load Mismatch ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 125 \text{ W}$ , $f = 400 \text{ MHz}$ , $VSWR = 30:1$ , all phase angles)	$\psi$	No Degradation in Output Power			

**NOTES:**

1. Each transistor chip measured separately.
2. Both transistor chips operating in push-pull amplifier.

\* Indicates JEDEC Registered Data.

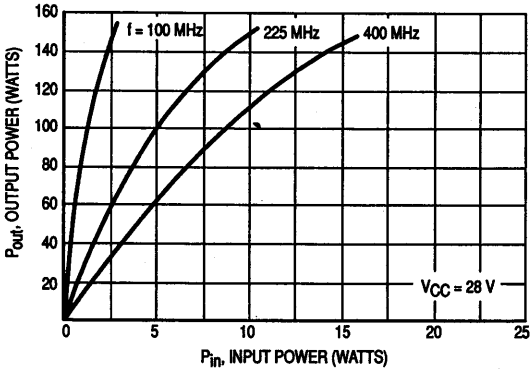


- C1, C2 — 240 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C3 — 4.7 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C8 — 12 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C5 — 27 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C6 — 20 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C7 — 12 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C9, C10 — 270 pF, 100 Mil Chip Cap (ATC) or Equivalent  
 C11, C12, C16, C17 — 470 pF 100 Mil Chip Cap (ATC) or Equivalent  
 C13, C18 — 680 pF Feedthru  
 C14, C19 — 0.1  $\mu\text{F}$  Erie Redcap or Equivalent  
 C15 — 20  $\mu\text{F}$ , 50 V  
 L1, L2 — 0.15  $\mu\text{H}$  Molded Choke With Ferrite Bead  
 L3, L4 — 2-1/2 Turns #20 AWG, 0.200 ID  
 L5, L6 — 3-1/2 Turns #18 AWG, 0.200 ID

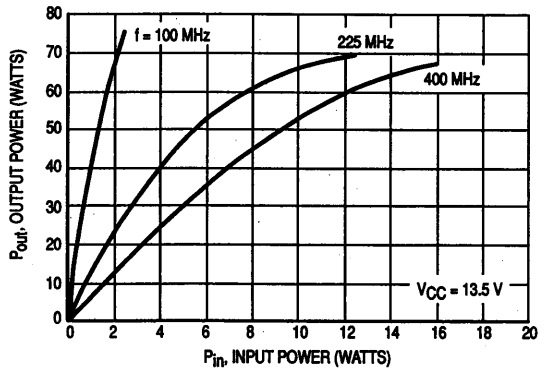
- B1 — Balun, 50  $\Omega$  Semi-Rigid Coaxial Cable 86 Mil OD, 2" L  
 B2 — Balun, 50  $\Omega$  Semi-Rigid Coaxial Cable 86 Mil OD, 2" L  
 Z1 — Microstrip Line 650 Mil L x 125 Mil W  
 Z2 — Microstrip Line 220 Mil L x 125 Mil W  
 Z3 — Microstrip Line 280 Mil L x 125 Mil W  
 Z4 — Microstrip Line 300 Mil L x 125 Mil W  
 Z5 — Microstrip Line 450 Mil L x 125 Mil W  
 Board Material — 0.06" Teflon-Fiberglass,  $\epsilon_r = 2.55$ ,  
 2 oz. Cu. CLAD, Double Sided

**Figure 1. 400 MHz Test Fixture**

**CLASS C**

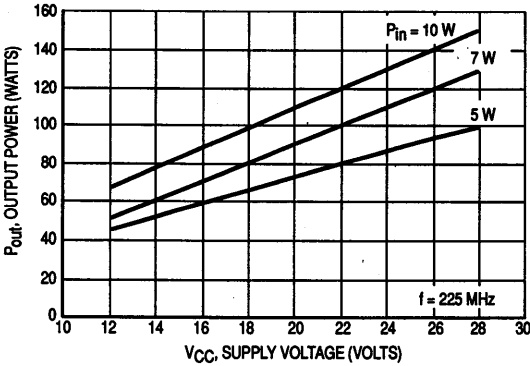


**Figure 2. Output Power versus Input Power**

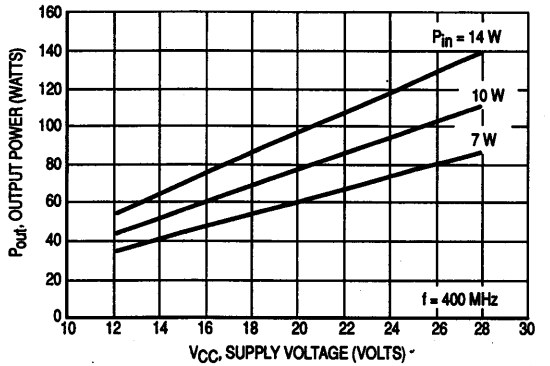


**Figure 3. Output Power versus Input Power**

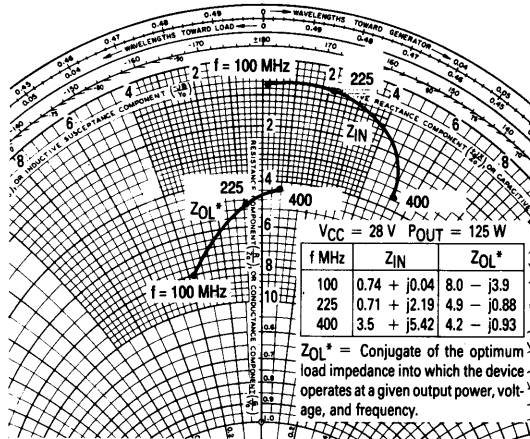
**CLASS C**



**Figure 4. Output Power versus Supply Voltage**

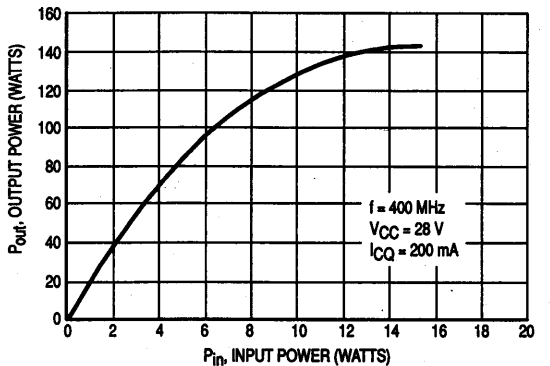


**Figure 5. Output Power versus Supply Voltage**



**Figure 6. Series Equivalent Input/Output Impedance**

Input and output impedances are measured from base to base and collector to collector respectively.

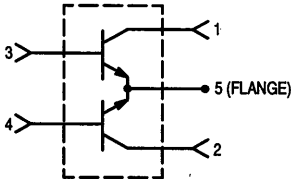


**Figure 7. Class AB Output Power versus Input Power**

The RF Line  
**NPN Silicon Push-Pull**  
**RF Power Transistor**

... designed primarily for wideband large-signal output and driver amplifier stages in the 30 to 500 MHz frequency range.

- Specified 28 Volt, 500 MHz Characteristics —  
 Output Power = 100 W  
 Typical Gain = 10.3 dB (Class AB); 9.0 dB (Class C)  
 Efficiency = 55% (Typ)
- Built-In Input Impedance Matching Networks for Broadband Operation
- Push-Pull Configuration Reduces Even Numbered Harmonics
- Gold Metallization System for High Reliability
- 100% Tested for Load Mismatch
- Hermetic Package to Meet Stringent Environmental Requirements



The 2N6986 is two transistors in a single package with separate base and collector leads and emitters common. This arrangement provides the designer with a space saving device capable of operation in a push-pull configuration.

**MAXIMUM RATINGS\***

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	30	Vdc
Collector-Base Voltage	V <sub>CB0</sub>	60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	4.0	Vdc
Collector Current — Continuous	I <sub>C</sub>	16	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C (1) Derate above 25°C	P <sub>D</sub>	270 1.54	Watts W/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C
Junction Temperature	T <sub>J</sub>	200	°C

**THERMAL CHARACTERISTICS**

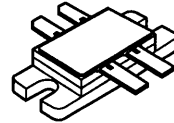
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub>θJC</sub>	0.65	°C/W

NOTE:  
 1. These devices are designed for RF operation. The total device dissipation rating applies only when the devices are operated as RF push-pull amplifiers.

\* Indicates JEDEC Registered Data.

**2N6986**

**100 W, 30 to 500 MHz**  
**CONTROLLED "Q"**  
**BROADBAND PUSH-PULL**  
**RF POWER TRANSISTOR**  
**NPN SILICON**



**CASE 382, STYLE 1**

**ELECTRICAL CHARACTERISTICS\*** ( $T_C = 25^\circ\text{C}$  unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS (1)**

Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $I_B = 0$ )	$V_{(BR)CEO}$	30	—	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $V_{BE} = 0$ )	$V_{(BR)CES}$	60	—	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 5.0 \text{ mAdc}$ , $I_C = 0$ )	$V_{(BR)EBO}$	4.0	—	—	Vdc
Collector Cutoff Current ( $V_{CB} = 30 \text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	—	—	5.0	mAdc

**ON CHARACTERISTICS (1)**

DC Current Gain ( $I_C = 1.0 \text{ Adc}$ , $V_{CE} = 5.0 \text{ Vdc}$ )	$h_{FE}$	20	—	100	—
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**DYNAMIC CHARACTERISTICS (1)**

Output Capacitance ( $V_{CB} = 28 \text{ Vdc}$ , $I_E = 0$ , $f = 1.0 \text{ MHz}$ )	$C_{ob}$	—	75	115	pF
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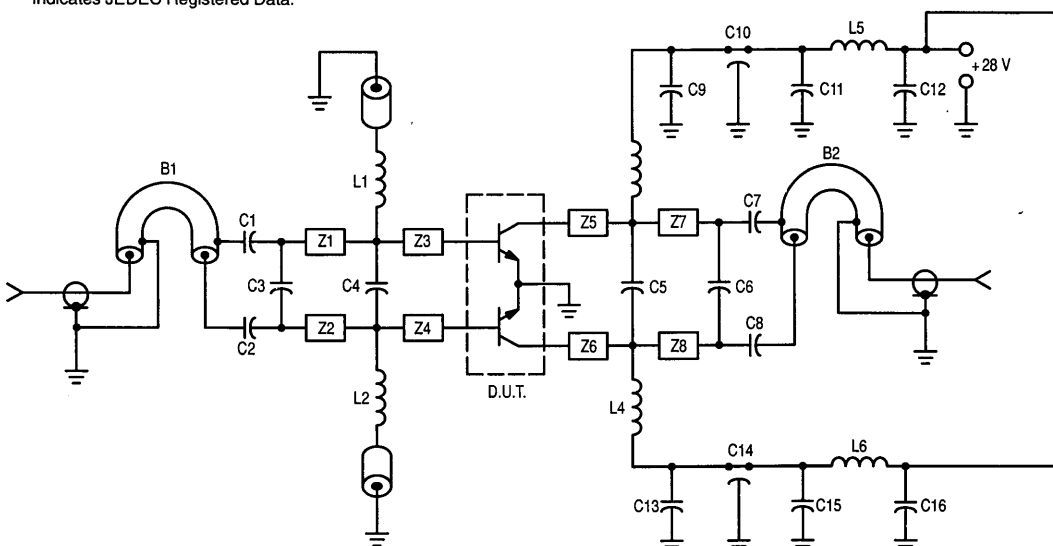
**FUNCTIONAL TESTS (2) — See Figure 1**

Common-Emitter Amplifier Power Gain ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 100 \text{ W}$ , $f = 500 \text{ MHz}$ )	$G_{pe}$	7.5	9.0	—	dB
Collector Efficiency ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 100 \text{ W}$ , $f = 500 \text{ MHz}$ )	$\eta$	50	55	—	%
Load Mismatch ( $V_{CC} = 28 \text{ Vdc}$ , $P_{out} = 100 \text{ W}$ , $f = 500 \text{ MHz}$ , $V_{SWR} = 30:1$ , all phase angles)	$\psi$	No Degradation in Output Power			

**NOTES:**

1. Each transistor chip measured separately.
2. Both transistor chips operating in push-pull amplifier.

\* Indicates JEDEC Registered Data.

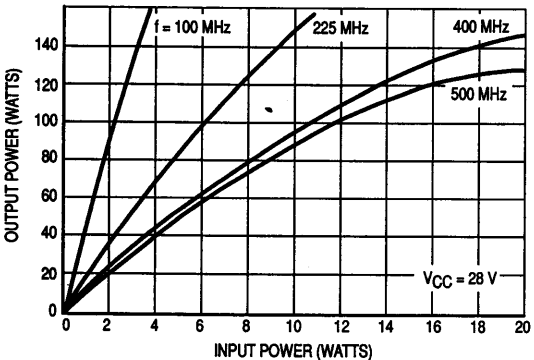


C1, C2, C7, C8 — 240 pF 100 mil Chip Cap  
 C3 — 12 pF 100 mil Chip Cap  
 C4 — 10 pF 100 mil Chip Cap  
 C5 — 36 pF 100 mil Chip Cap  
 C6 — 12 pF 100 mil Chip Cap  
 C9, C13 — 1000 pF 100 mil Chip Cap  
 C10, C14 — 680 pF Feedthru Cap  
 C11, C15 — 0.1  $\mu\text{F}$  Ceramic Disc Cap  
 C12, C16 — 50  $\mu\text{F}$  50 V

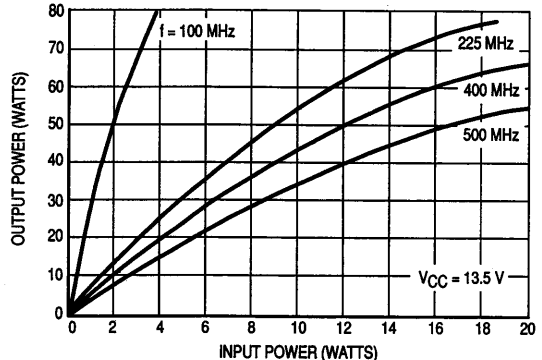
L1, L2 — 0.15  $\mu\text{H}$  Molded Choke with Ferrite Bead  
 L3, L4 — 2-1/2 Turns #20 AWG 0.200" ID  
 L4, L5, L6 — 3-1/2 Turns #18 AWG 0.200" ID  
 B1, B2 — Balun 50  $\Omega$  Semi Rigid Coax, 86 mil OD, 2" Long  
 Z1, Z2 — 450 mil Long x 125 mil W. Microstrip  
 Z3, Z4 — 340 mil Long x 125 mil W. Microstrip  
 Z5, Z6 — 280 mil Long x 125 mil W. Microstrip  
 Z7, Z8 — 600 mil Long x 125 mil W. Microstrip  
 Board Material — 0.03" Teflon-Fiberglass,  $\epsilon_r = 2.55$ ,  
 2 oz. Copper Clad both sides.

**Figure 1. 500 MHz Test Fixture**

**CLASS C**

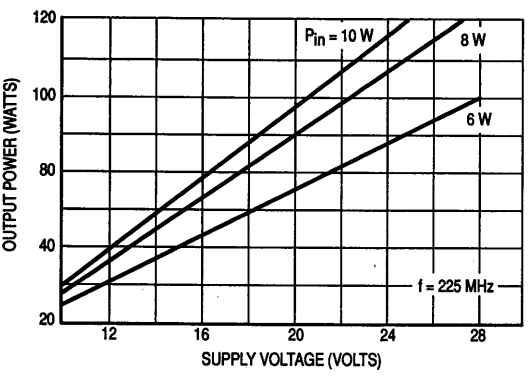


**Figure 2. Output Power versus Input Power**

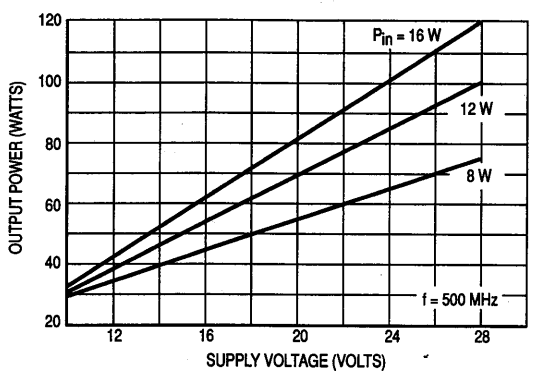


**Figure 3. Output Power versus Input Power**

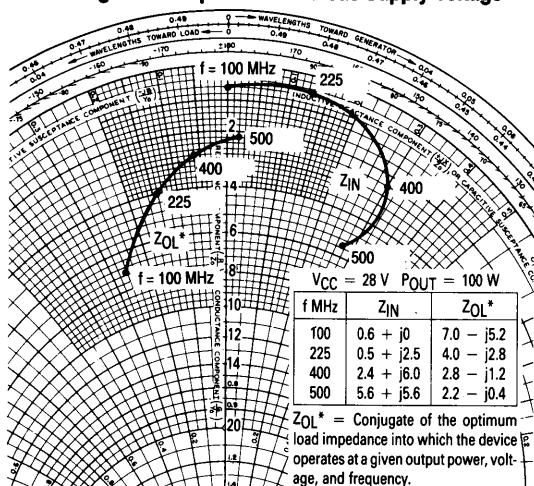
**CLASS C**



**Figure 4. Output Power versus Supply Voltage**

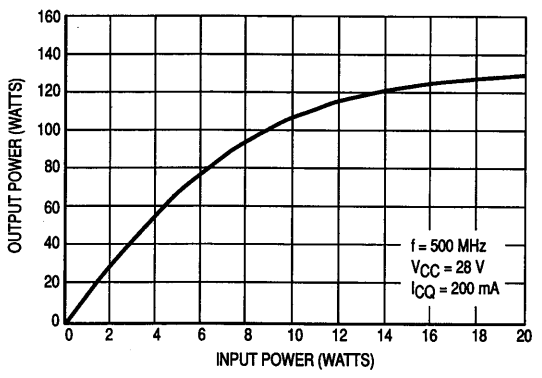


**Figure 5. Output Power versus Supply Voltage**



**Figure 6. Series Equivalent Input/Output Impedance**

Input and output impedances are measured from base to base and collector to collector respectively.



**Figure 7. Class AB Output Power versus Input Power**